



PRODUCT SPECIFICATION

(產品規格書)

Ordering information

9111-	A42	24	11	CB	30	D	T-A001
Series	4:4Rows 2:Female	Position	1:Dip Lenght 2:Dip Lenght	C:Dip Tin Contact Gold G:Gold	10:10μ” 30:30μ”	D:Dip Type P:Press Fit Type	U:Tube Package
9111-	45	24	B1	CB	30	D	T-A001
Series	5:5Rows 2:Female	Position	1:Dip Lenght 2:Dip Lenght	C:Dip Tin Contact Gold G:Gold	10:10μ” 30:30μ”	D:Dip Type P:Press Fit Type	U:Tube Package

A1:JUL.07/2015.(I800)

PRODUCT NAME (產品名稱)	DOCUMENT No.: (文件編號)	Rev. (版本)	OUPIIN (歐品)
H.D. 2.0mm Futurebus+ Female (RoHS)	9111spec-A42&45	A3(I800)	
	Approved (核準)	Checked (審核)	Prepared (製作)
	Q.A. Section Chief	Amy Chiu	JUL.07/2015



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1. SCOPE (範圍)

This product specification defines the product performance and the test methods to ascertain the performance of the H.D. 2.0mm Futurebus+ , which is designed and manufactured by Oupiin Electronic Co.,Ltd.

(本產品規格書規定了由歐品電子有限公司生產的 H.D. 2.0mm Futurebus+ 型連接器,產品的特性及測試方法.)

2. REFERENCE DOCUMENTS (參考文件)

MIL-STD-1344	Test method for electrical connector (電子連接器測試方法)
MIL-STD-202	Test method for electrical components (電子零件測試方法)
EIA 364	Test method for electrical components (電子零件測試方法)

3. FEATURE & DIMENSIONS (特徵及尺寸)

3.1. PRODUCT DIMENSION (產品尺寸)

These connectors shall have the dimensions as shown in drawing.

(本產品的相關尺寸參考圖面.)

3.2. PCB/PANEL LAYOUT (印刷電路板佈局)

The recommended PCB layout is shown in drawing.

(本產品適用的 PCB layout 參考圖面.)

3.3. BILL OF MATERIAL (材料清單)

Harmful material control follow the requirement of RoHS. The bill of material and product number is described in drawing.

(有害物質控制符合RoHS指令要求.本產品使用的材料參考附件.)

3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC (機械及電氣特性)

The connector shall have the mechanical and electrical performance as described in drawing.

(本產品的機械及電氣特性見圖面：)

3.5. PACKAGING (包裝)

Products shall be packaged according to requirements specified in purchase order for safe delivery, connector container and the packaging method are shown in package specification.

(產品可依客戶指定要求包裝，包裝材料與包裝方式參見產品包裝規範。)

3.6 RATING CURRENT AND RATING VOLTAGE 額定電流與額定電壓

Rating current is 1.0A, rating voltage is 250V DC/AC RMS.

額定電流 1.0A，額定電壓 250V DC/AC RMS。

3.7 OPERATING TEMPERATURE 使用溫度

Temperature range: -55°C~+125°C,

溫度範圍：-55°C~+125°C。

4. ENVIRONMENTAL (環境要求)

4.1. SOLDERABILITY (可焊性)

Connectors meet solder ability to MIL-STD-202. Finish shall be free of contaminants.

(產品可焊性符合 MIL-STD-202 標準規定的相關要求，表面不得有污染物.)

4.2. RESISTANCE TO SOLDER HEAT (耐焊接熱)

WAVE SOLDERING (波峰接)

Each cycle consists of three consecutive phases.

(每個焊接週期包括三個連續的階段)

1. Preheat (預熱)

The steady temperature of the preheat zone is 90~125°C.

(預熱區最終溫度控制在90~125°C)

2. Soldering (焊接)

To avoid the secondary tin-melting, the temperature on PCB upper surface is 160°C Max. for products with lead, or 200°C Max. for lead-free products. The temperature of the PCB bottom surface shall not be exceed 100°C more than the temperature of the PCB upper surface. The peak temperature is during 220~250°C for products with lead, or 235~265°C for lead-free products. The tin dip time is duration for 3~10 seconds.

(有鉛產品板面溫度不得超過160°C，無鉛產品板面溫度不得超過200°C，以防止貼片零件二次熔錫。板面溫度與板底的溫度溫差不得超過100°C。板下溫度峰值有鉛產品維持在220~250°C，無鉛產品控制在235~265°C。浸錫時間控制在3~10秒。)

3. Cool Down (冷卻)

Cool down shall not exceed 6°C per second.

(冷卻速度不超過6°C/秒.)

Note: (說明)

Device temperature measurements are referenced from the top-center of the package outer surface.

(設備溫度量測時以從頂部中間位置測量為準.)

5. PERFORMANCE AND TEST DESCRIPTION

(性能及測試)

5.1. REQUIREMENT (要求)

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

(本產品設計符合附表一所述的機械，電氣及環境要求。)

5.2. TEST CONDITION (測試條件)

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

(除非特別注明，所有測試在室溫條件下完成；)

5.3. SAMPLE SELECTION (樣品選擇)

Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.

(測試樣品從現生產的產品中隨機抽取，所有測試過的樣品不得重複使用。樣品已預先插拔10次，每組測試有5個樣品；)

Table I: Test Requirements and Procedures

(附錄一:測試要求)

Items (項目)	Requirements (要求)	Test Methods (檢測方法)
1. Confirmation of Product (產品確認)	Product shall be conforming to the requirements of applicable product drawing. (產品必須滿足相關檔的規定)	Check the dimensions and functions per applicable product drawing in your eyes. (目視，尺寸及功能依產品圖面檢查)
2. Contact Resistance (接觸阻抗)	Row a 25 mΩ Max. Row b 35 mΩ Max. Row c 40 mΩ Max. Row d 45 mΩ Max. (最大電阻)	Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 20 mV max. (所述固定在外殼裏的端子連結到一個封閉回路中測試：電流 100 mA，電壓 20 mV max.) EIA-364-23
3. Insulation Resistance (絕緣阻抗)	1000 MΩ Min. (最小)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC±10%). (測試產品端子間以及端子與接地間的電阻，適用：MIL-STD-202,方法 302，條件 B)(500V DC±10%)
4. Dielectric Strength (耐電壓)	Connector must withstand test potential of 1000 V AC for 1 minute. Current leakage must be 0.5 mA max. (樣品必須承受測試電壓 1000V AC，時間一分鐘，漏電流不大於 0.5 mA.)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. EIA-364-20 (測試產品端子間以及端子與接地間的電壓，適用：EIA-364-20)
5. Durability (耐久性)	Contact Resistance: 30 mΩ Max. after testing. (測試後接觸阻抗最大 30mΩ)	The sample should be mounted the tester and fully mated and unmated 250 cycles specified at the rate of 100 cycles/hour. (重復進行配合產品 250 次插拔.) Frequency of operations: 100 cycles/h Speed of operations:10 mm/s max. Rest:30 s, unmated.
6. Connector Insertion/Withdrawal Force	Insertion force : (插入力: 0.45 N 最大) 0.45 N max. Per individual contact Withdrawal force :	Measure force necessary to unmated between the counterparts connectors.. (軸向力以 25±3mm/分的速度從塑膠本體對插後拔)



PRODUCT SPECIFICATION OF OUPIIN

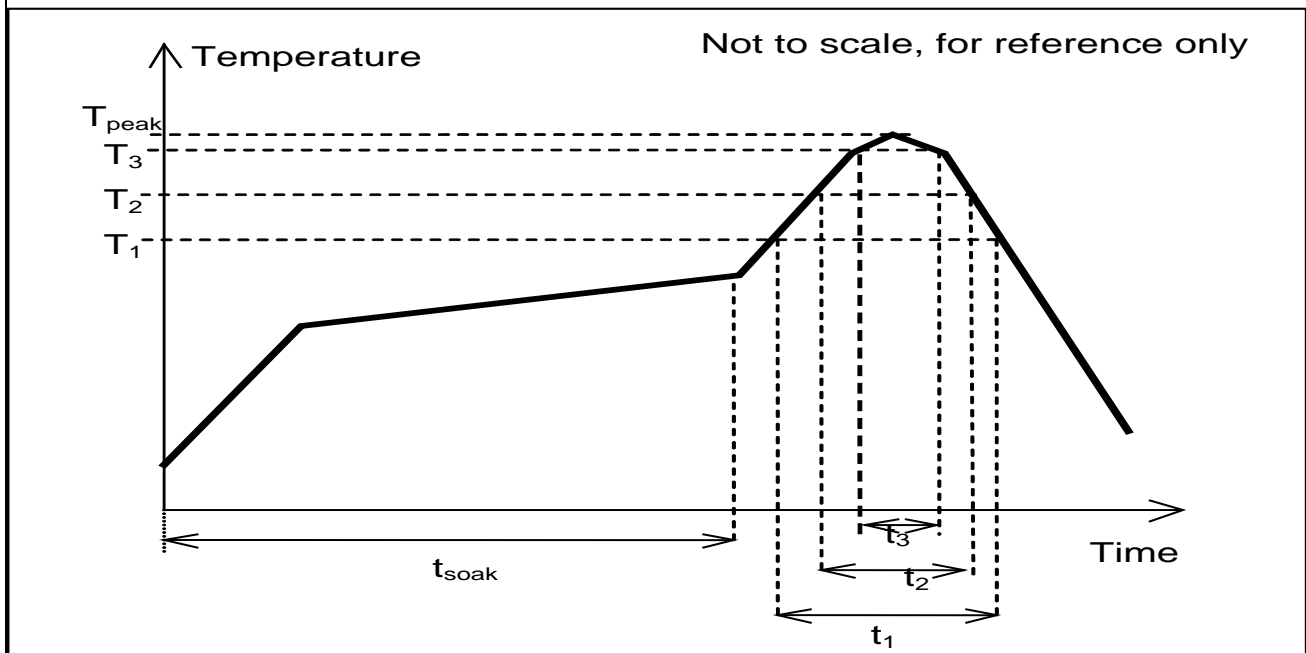
(產品插拔力)	0.15 N min. per individual contact 單孔拔出力: 0.15 N 最小	出)
7. Thermal shock (熱衝擊)	After testing, no damage, Contact Resistance Rise in relation to initial values 5 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 1000 MΩ min. (測試後接觸阻抗比初始值增大不超過 5mΩ ; 耐電壓測試 OK, 絕緣阻抗 1000MΩ 最小;)	Temperature range from -55°C to +85°C .Start from -55°C, after 30 min. change to +85°C; change time is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D, condition A. (溫度變化範圍: -55°C ~ +85°C ; 從 -55°C 開始, 30 分鐘後換到+85°C ; 轉換時間不超過 30 秒 ; 共 5 個循環.適用: MIL-STD-202, 方法 107D, 條件 A.)
8. Humidity (恆溫恆濕)	After testing, no damage, Resistance Rise in relation to initial values 5 mΩ max. (測試後,產品無損壞, 測試後接觸阻抗比初始值增大不超過 5mΩ)	Temperature : 85±2°C 96 hours. (溫度: 85±2°C 96 小時) Relative Humidity : 90-95%; (相對濕度 : 90-95%;) Duration :96 Hours. MIL-STD-202, Method 108, (時間: 96 小時; MIL-STD-202, 方法 108。)
9.High Temperature Life (高溫老化)	After testing, no damage, Resistance Rise in relation to initial values 5 mΩ max. (測試後,產品無損壞, 測試後接觸阻抗比初始值增大不超過 5mΩ)	Subject product to 125±3°C for 96 hours continuously. MIL-STD-202, Method 108. (產品置於 125±3°C 連續 96 小時, 適用 MIL-STD-202, 方法 108。)
10. Salt Spray (鹽霧)	After testing, no damage, Resistance Rise in relation to initial values 10 mΩ max. (測試後,產品無損壞, 測試後接觸阻抗比初始值增大不超過 10mΩ)	5±1% salt concentration 48 hours 35±2°C MIL-STD-202, Method 101 Condition B. (鹽水濃度 (重量比) 5±1%, 時間 48 小時, 溫度 35±2°C ; MIL-STD-202, 方法 101 條件 B.)
11. Solder ability (可焊性)	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10 X for any damage such as pinholes, void or rough surface. (樣品在測試完成後, 在放大倍數為 10 倍的顯微鏡下, 檢查外觀損壞如: 小孔, 空焊, 外觀粗糙度;)	Soldering time: 3 to 5 Seconds (焊接時間: 3~5 秒) Peak Temperature: 260±5°C. (最高溫度: 260±5°C.)

Table II: Reflow soldering profile

(附錄二:回流焊接曲線圖)

Pb-free reflow profile requirements: (無鉛回流焊接曲線)

Parameter (參數)	Reference (參考)	Specification (規格)
Average Temperature Gradient in Preheating (平均預熱溫度)		2.5°C/s
Soak Time 25~150°C	T_{soak}	60 Seconds (max)
Time Above 150~210°C	t_1	120 Seconds (max)
Time Above 210~230°C	t_2	60 Seconds (max)
Time Above 230~255°C	t_3	10 Seconds (max)
Peak temperature in reflow (回流焊接中最高溫度)	T_{peak}	260°C (-5/+0°C)
Temperature Gradient in Cooling (冷卻時溫度幅度)		Max -5°C/s



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

(這個曲線圖是評估原器件焊接抗熱的基本要求。應用在對流焊接中的熱傳遞方式是熱氣對流。達到特定曲線圖的實際溫度主要依賴於回流焊接設備。)



PRODUCT SPECIFICATION OF OUPIIN

Material Housing : 070-LCP

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Technical Data

Liquid Crystalline Polymer Compound

LONGLITE® LCP 270B3G / 270N3G

LCP-270B(N)3G is liquid crystalline polymer which contains 30% glass fiber.

LCP-270B(N)3G has advantages of high heat resistance, strength and good flowability.

Physical Properties :

Items	Unit	Test Method	270B3G* 270N3G
Features	heat resistance/low warpage		
Filler	%	---	Glass Fiber
Filler Content		ASTM	30
Specific Gravity	---	D792	1.62
Water Absorption	%	D570	0.04
Shrinkage	MD	CCP method	0.19
	TD		0.39
Tensile Strength(RT)	MPa	D638	122
Tensile Elongation(RT)	%		1.8
Flexural Strength (RT)	MPa	D790	190
Flexural Modulus (RT)	GPa		12.5
Izod Impact (3.0t/w notched)	J/m	D256	110
HDT (264 psi)	°C	D648	270
Dielectric Strength	KV/mm	D149	19
Arc Resistance	sec	D495	150
UL-94(NC, BK)	Rating	UL94	V-0
Tracking Resistance (CTI)	V	D257	125
Dielectric Constant / Dk	---	10 ⁶ Hz (1 MHz)	4.5
Dielectric Tangent / Df	---	10 ⁶ Hz (1 MHz)	0.036

* Typical data : Not to be constructed as specification

LCP-270B(N)3G B : Black N : Natural color



Material Housing :UL

UL iQ™ for Plastics

Page 1 of 1

Component - Plastics

E59481

CHANG CHUN PLASTICS CO LTD
7TH FL, 301 SONGKIANG RD, TAIPEI 104 TW

270(X1)3G

Liquid Crystal Polymer (LCP), "LONGLITE", furnished as pellets

Table with 7 columns: Color, Min Thk (mm), Flame Class, HWI, HAI, RTI Elec, RTI Imp, RTI Str. Rows for BK at 0.3, 1.0, and 3.0 mm thickness.

Comparative Tracking Index (CTI): 4
Dielectric Strength (kV/mm): -
High-Voltage Arc Tracking Rate (HVTR): 2
Dimensional Stability (%): -
Inclined Plane Tracking (IPT): -
Volume Resistivity (10^9 ohm-cm) : -
High Volt, Low Current Arc Resis (D495): 5

(X1) - Maybe replace by one letter N representing Natural color or B representing Black color

ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.

Report Date:2013-07-12
Last Revised:2013-07-12

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IEC and ISO Test Methods

Table with 5 columns: Test Name, Test Method, Units, Thickness Tested (mm), Value. Lists various IEC and ISO test methods and their results.

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Material Contact : Copper Alloy (Brass)

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REPORT OF MATERIAL TEST
材料測試報告

ISO 9001
ISO/TS 16949
IECQ QC080000
ISO 14001
OHSAS 18001 & TOSHMS

No. : 3C1556

DATE: DEC.26,2014

Customer 顧客名稱 : 歐品電子有限公司
Commodity 商品名稱 : C 2680 R BRASS STRIP (H)
Applied Standard 引用標準 : JIS H 3100 Copper and Copper alloy sheets, plates and strips

Manufacture No.	銅捲製號	3AA046A	
(Specification)	產品規格	Standard	
Thickness (mm)	產品厚度		0.400
Width (mm)	產品寬度		27.500
Length (mm)	產品長度		
(Chemical Analysis Test)	化性測試		
Cu(%)	銅	64.000-68.000	64.947
Fe(%)	鐵	max. 0.050	0.013
Pb(%)	鉛	max. 0.0500	0.0003
Zn(%)	鋅	REM.	REM.
(Mechanical & Physical Test)	物性測試		
Thickness Test (mm)	厚度測試	-0.015 +0.010	0.394
Width Test (mm)	寬度測試	-0.10 +0.00	GOOD
Tensile Strength (kgf/mm2)	抗拉強度	42.00 - 55.00	51.06
Elongation (%)	伸長率	-	17.92
Hardness Test (Hv)	硬度	140.0 - 160.0	158.0 - 160.0
Grain Size (mm)	結晶粒度	-	0.015
Electric Conductivity (%)	導電率	-	26.20
(Other Information)	其他資訊		
Delivery No.	出貨單號	3CA079	
Customer Purchase Order	採購單號	PO.B02A14101603	



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